

E1.S 4TS2-P

HIGHLIGHT FEATURES



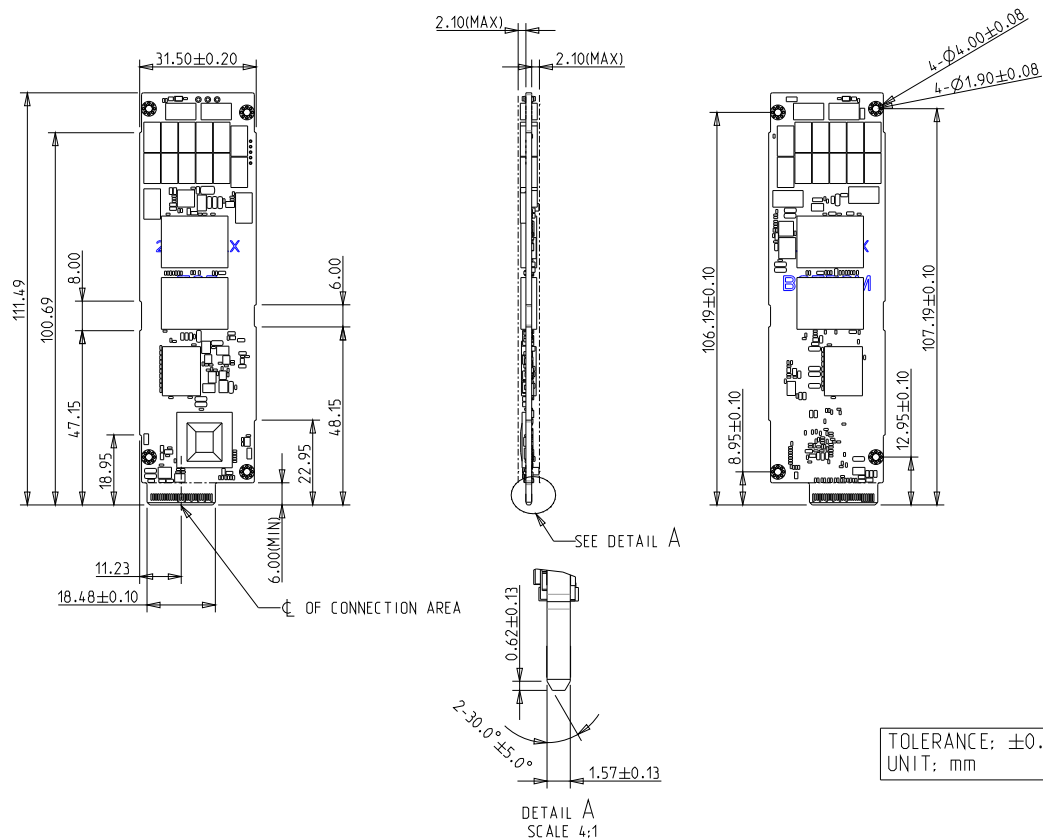
- PCIe Gen 4 x4, NVMe 1.4
- PLP (iCell) technology for power loss protection
- Stable sustained performance
- LDPC ECC engine supported
- Dynamic thermal management

SPECIFICATIONS

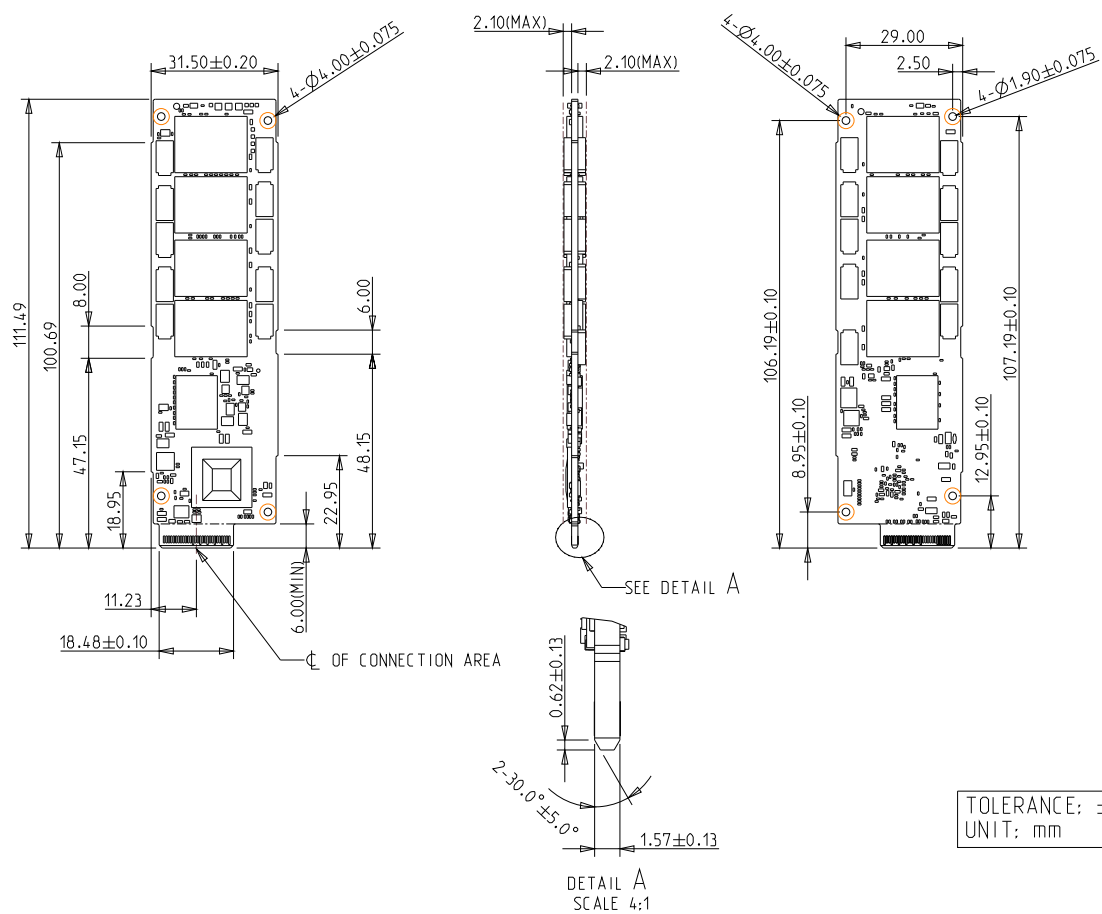
Model Name	E1.S 4TS2-P
Flash Type	3D TLC
Interface	PCIe Gen 4 x4
Form Factor	E1.S
Capacity	400GB ~ 6.4TB
Sequential R / W (MB/sec, max.)	6,900 / 4,650
P/E Cycle	3,000
TBW (Max.)	9,400
Storage Temperature	-40°C ~ 85°C
Max. Power Consumption	12.4W
Max. Channels	8
External DRAM Buffer	Y
H/W Write Protect	N
S.M.A.R.T.	Y
AES	Y
TCG Opal	Y
Dimension (W x L x H/mm)	5.9mm : 31.5 x 111.5 x 5.9 9.5mm : 33.75 x 118.75 x 9.5 15mm : 33.75 x 118.75 x 15.0
Vibration	20G@[7 ~ 2000Hz]
Shock	1500G@0.5ms
MTBF	>3 million hours
Warranty	5 Years

DIAGRAM

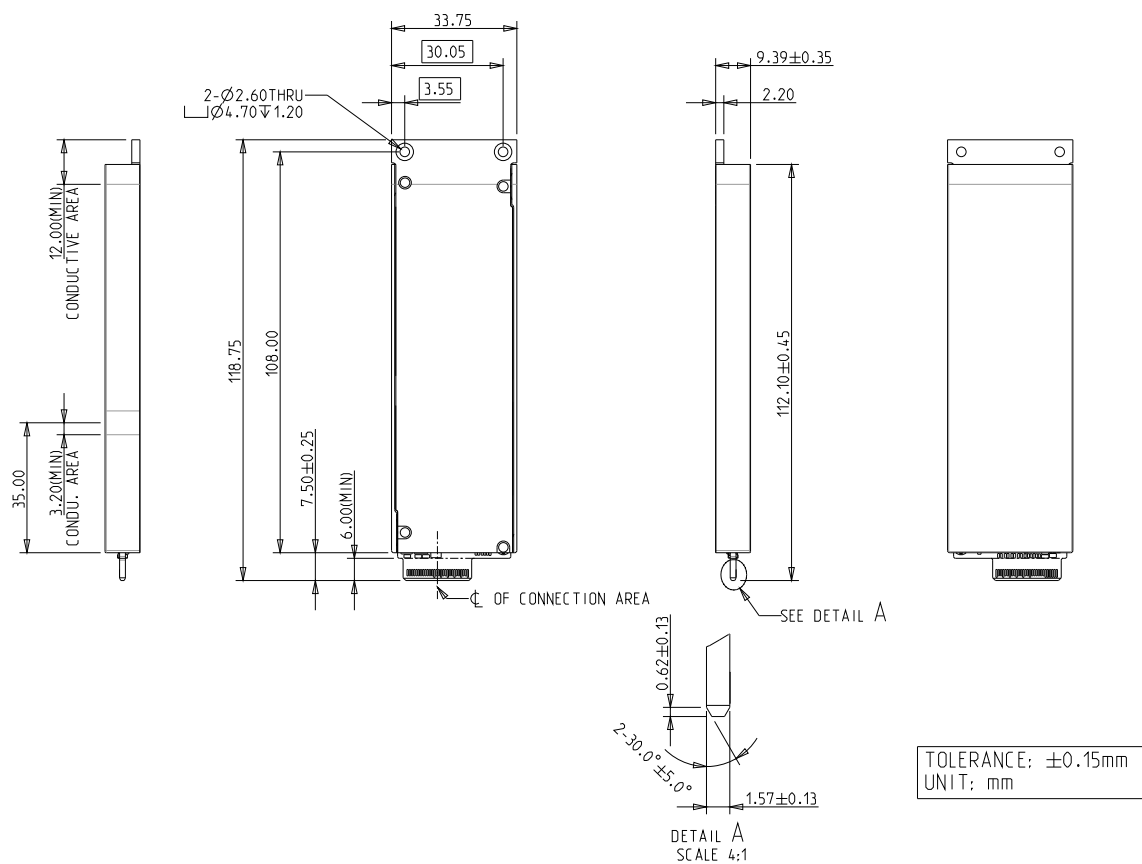
5.9mm (400GB ~ 3.2TB)



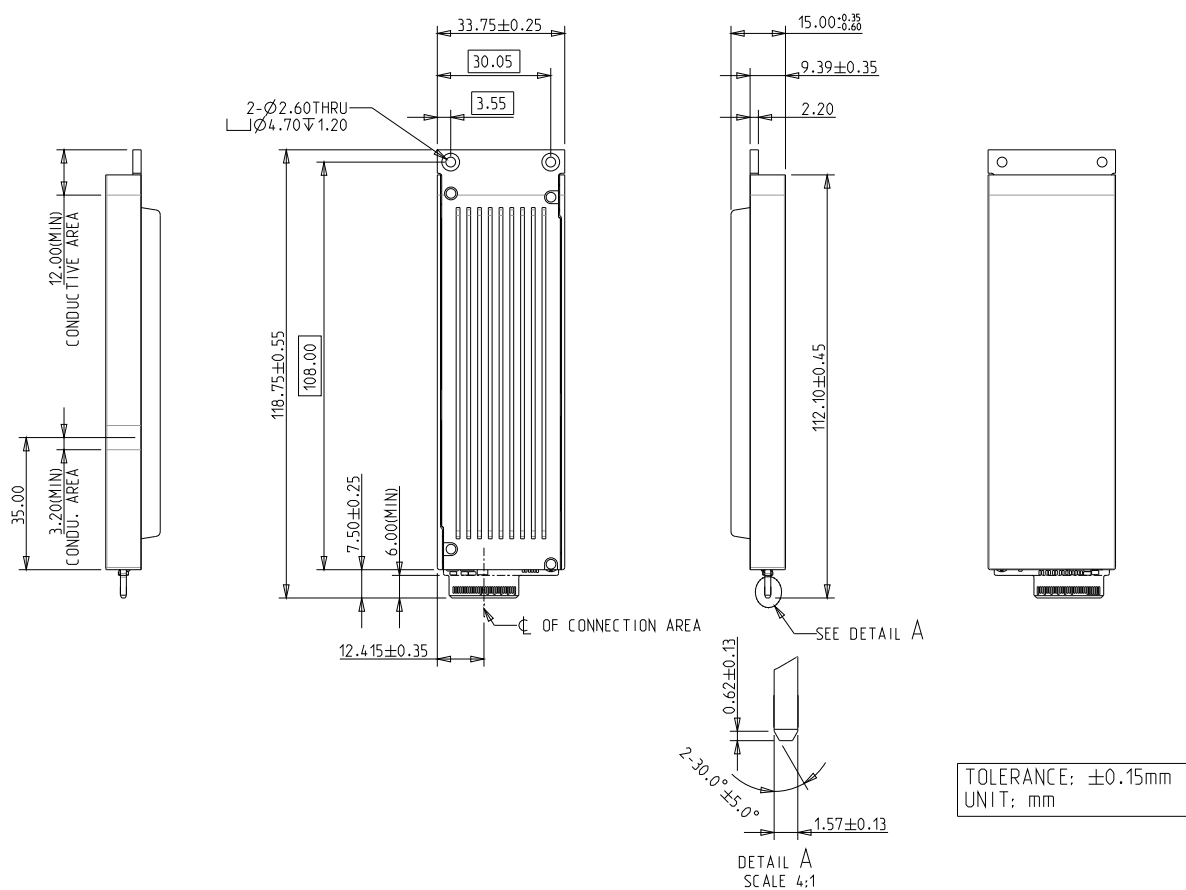
5.9mm (6.4TB)



9.5mm



15mm



ORDER INFO.

Operating Temperature	Standard Grade (0°C ~ 70°C)	Industrial Grade (-40°C ~ 85°C)
400GB	DSE1S-400DP2KCAEFP%	DSE1S-400DP2KWAEFP%
800GB	DSE1S-800DP2KCAEFP%	DSE1S-800DP2KWAEFP%
1.6TB	DSE1S-1T6DP2KCAEFP%	DSE1S-1T6DP2KWAEFP%
3.2TB	DSE1S-3T2DP2KCAEFP%	DSE1S-3T2DP2KWAEFP%
6.4TB	DSE1S-6T4DP2KCBEP%	DSE1S-6T4DP2KWBEFP%

Operation temperature based on temperature obtained from S.M.A.R.T.
% : Non-existent=5.9mm / H=9.5mm enclosure / H1=15mm enclosure
E1.S 4TS2-P specifications are subject to change.